3RD GENERATION PARTNERSHIP PROJECT 2
"3GPP2"

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Mr. Nigel Barnes
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Re: UICC form factors

Dear Mr. Barnes,

Due to an oversight due to the TSG-C leadership transition, your correspondence regarding the third form factor for Smart Card (Tdoc SCP-030066) was not brought to my attention until the most recent meeting. I thank you for your considerations and would also like to provide the status of the UICC related activities in 3GPP2.

3GPP2 has just started looking into the UICC related work. A new work item on supporting ISIM through UICC card has just been approved and; moreover there are also discussions about migrating the R-UIM to the UICC platform. However, the group has not yet had the opportunity to assess the impact of the new form factor. To maintain the compatibility with UICC specifications, we most likely will adopt direct referencing to the ETSI-SCP documents for the common sections and focus on adding the technical aspects catering to the 3GPP2 operations.

Should you have further questions or updates, please contact our liaison to ETSI-SCP, Mr. Gordon Beatty (Gemplus) gordon.beatty@gemplus.com.

Regards,

Hideo Okinaka
Chair, 3GPP2 SC

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